

I am submitting a revised version of the paper, where I have taken care of the remarks made by the reviewer to the manuscript, as I detail below.

Minor changes requested

Page 1: These large vias can be used in the periphery.....to the external world. => I know what is meant but the expression is a bit hard to understand.

I have changed this sentence, I hope this is now explained in a better way.

*Page 1: eliminating most if not all **of** the chip dead area*

Corrected.

Page 3: The tapered vias have a bottom diameter of about 100 μm at the bottom... => remove the first 'bottom'

Done (this is now at the beginning of page 4).

Page 5: and consecutive back etching => replace etching by thinning (EMFT uses chemical and mechanical means)

Done

Page 5: 3. 3D Integration => looks like 3.3 D. perhaps say: AIDA activities for 3D integration of imaging sensors ?

Done

Figure 4: I think the $3\mu\text{m} \times 10\mu\text{m}$ are the four black rectangles in the brown area?

I corrected the caption of this figure (it is actually Fig. 5; in the first version of the paper some figures were incorrectly numbered).

Page 7: For a description and evaluation of the Tezzaron/Fermilab process you could cite R. Yarema's talk in the same proceedings (vertex13_032).

I included this paper as reference [14].

Page 8: of the future very demanding applications at => of very demanding future applications at

Done.

Page 8: showed => shown

Done.

Page 8: proved => proven

Done.

Reference [7]: please add a WWW link

Done

Reference [14]: replace by R. YaremaVertex2013 ?

Done

Reference [18]: 2013..

Done (it is now reference [19], since I added ref. [16])

Reference [20]: also here a WWW link is needed

Done (it is now reference [21])